#### Surface mount LVF Schottky diode Reverse Voltage40V-200v Forward current-5A

#### **Features**

LVF Schottky chip
Low VF, Low power losses, high efficiency
Ldeal for surface mounted applications
Plastic Case Material has UL Flammability

#### Mechanical Data

Package: SMA

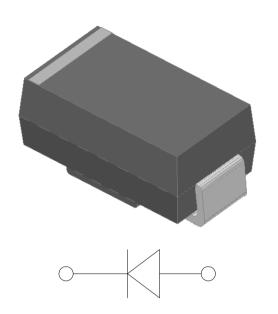
Terminals:Tin Plated leads, solderable per

Mil-STD-750 Method 2026

Polarity: As marked

Molding compound meets UL 94 V-0 flammability rating,

**ROHS-compliant** 



#### Maximum Ratings (Ta=25℃ Unless otherwise specified)

waxiinum Ratings (Ta-25 C Offiess otherwise spe	ecineu)								
Type Number	SYMBOL	SS 54L	SS 545L	SS56L	SS 58L	SS 510L	SS 515L	SS 520L	Umit
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	40	45	60	80	100	150	200	V
Maximum RMS Voltage	$V_{RMS}$	28	31.5	42	56	70	105	140	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	40	45	60	80	100	150	200	V
Maximum Average Forward Rectified Current	IO <sub>(AV)</sub>	5.0						Α	
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load(JEDEC Method) on rated		100.0						А	
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25℃	- IFSM	200.0						А	
Current squared time @1ms≤t8.3≤ms Tj=25℃,Rating of per diode	I <sup>2</sup> t	41.5				A <sup>2</sup> S			
Maximum Forward Voltage at 5.0A DC	$V_{FM}$	0.	45	0.55	0.	65	0.	85	V
Maximum Reverse Current TA = 25 ℃	IR	0.2 0.1						A	
at Rated DC Blocking Voltage TA = 800 ℃		50.0 20.0				mA			
Typical Thermal Resistance Between junction and	$R_{QJa}$	65.0					°C/W		
Operating Junction Temperature Range	TJ	Γ <sub>J</sub> —55to+150			$^{\circ}$				
Storage Temperature Range	T <sub>STG</sub>	—55to+150				$^{\circ}$			

FIG. 1MAXIMUM AVERAGE FORWARD CURRENT DERATING

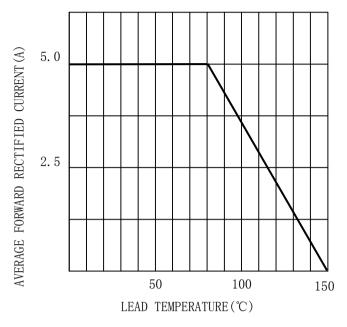


FIG. 2TYPICAL FORWARD CHARACTERISTICS

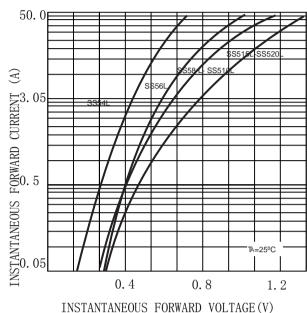


FIG. 3MAXIMUM NON-REPEITIVE SURGE CURRENT

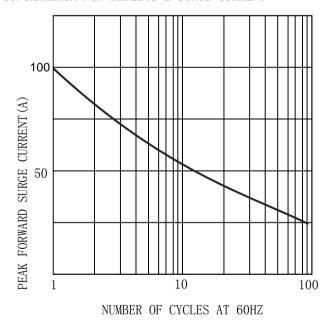
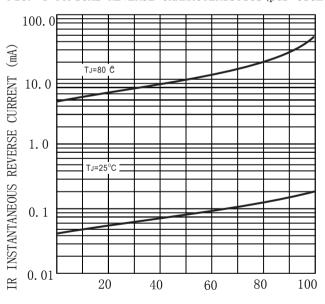


FIG. 4 TYPICAL REVERSE CHARACTERISTICS (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

### **MARKING INFORMATION**



🤝 = Logo

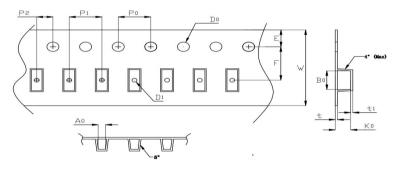
\*\*\*\* = Date Code Marking

SS\*\*\*L = Marking Code

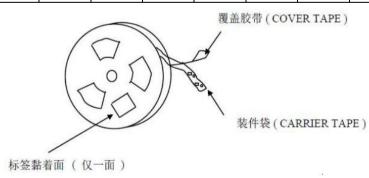
Print according to customer request

### **PACKING REQUIRMENTS**

Carrier tape packing



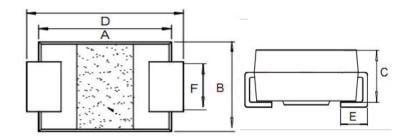
Specificati ons	Carrier tape type	Ao	Во	Ко	Ро	W	t	Exiplain
SMA	Anti-static	2.65± 0.10	5.20± 0.10	2.30± 0.10	4.00± 0.10	12.0± 0.10	0.20± 0.05	



DEVICE TYPE	Tape width		11"Reel		11"Reel		
		Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)	Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)
SMA	12mm	5000	20	100000	5000	18	90000

### Outline Dimensions

SMA



SMA							
DIM	INC	HES	MM				
	MIN	MAX	MIN	MAX			
A	0. 16	0. 18	4.05	4.65			
В	0.09	0. 11	2.4	2.8			
С	0.07	0.09	1.8	2. 3			
D	0.18	0.21	4.67	5. 27			
Е	0.04	0.06	1	1.4			
F	0.05	0.06	1.2	1.6			



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